

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen Top Silk Screen		Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.01 mm	Green	3.3	0
F.Cu	copper		0.03556 mm		1	0
Dielectric 1	core	R04350B	0.762 mm	FR4 natural	3.66	0.0037
B.Cu	copper		0.03556 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

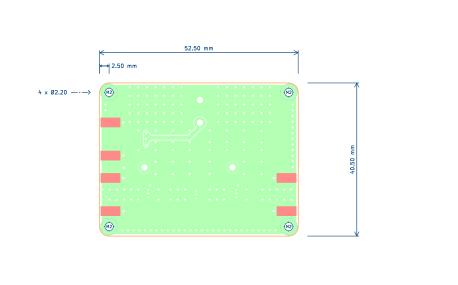
Note	5:				
LNA	footprint	is	pin-compatible	with	PMA2-123LN+.

Remy Nguyen

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Size: A4	Date: 7/6/2023	Rev: <sup>B</sup>
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Notes: LNA footprint is pin-compatible with PMA2-123LN+.

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Title: RF-DFS Gain Circuit

 Size: A4
 Date: 7/6/2023
 Rev: B

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